PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Chien-Chao Huang	09/13/2004
Cheng-Chuan Huang	05/02/2005
Fu-Liang Yang	09/22/2004

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	10937722

CH $40.00 10937722

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	David M. O'Dell

Total Attachments: 3
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Docket No.: 2003-1104/24061.202
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

(1)	Chien-Chao Huang	of	Hsin-Chu, Taiwan, R.O.C.
(2)	Cheng-Chuan Huang	of	Taipei County, Taiwan, R.O.C.
(3)	Fu-Liang Yang	of	Hsin-Chu City, Taiwan, R.O.C.

have invented certain improvements in

A STRAINED SILICON DEVICE MANUFACTURING METHOD

for which we have executed an application for Letters Patent of the United States of America,

_______ of even date filed herewith; and
__X__ filed on September 9, 2004 and assigned application number 10/937,722; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar ($1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chien-Chao Huang

Residence Address: 6F-1, No. 32, Ti-Yu Street
Hsin-Chu, Taiwan 300, R.O.C.
Taiwan, R.O.C.

Dated: ✓ Sep. 13, 2004

✓ Chien-Chao Huang
Inventor Signature

Inventor Name: Cheng-Chuan Huang

Residence Address:

Dated: ✓

✓
Inventor Signature

Inventor Name: Fu-Liang Yang

Residence Address: 7F-3, No. 68, University Road
Hsin-Chu City, Taiwan, R.O.C.

Dated: ✓ 22nd Sep 2004

✓ Fu-Liang Yang
Inventor Signature

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Docket No.: 2003-1104/24061.202
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and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:	Chien-Chao Huang
Residence Address:	6F-1, No. 32, Ti-Yu Street Hsin-Chu, Taiwan 300, R.O.C. Taiwan, R.O.C.

Dated:________________ ________________
Inventor Signature

Inventor Name:	Cheng-Chuan Huang
Residence Address:	9F-4, No. 46, Deguang Rd., Jhonghe City Taipei County, Taiwan, R.O.C.

Dated: ✓ 2005.05.02 ✓ Cheng-chuan Huang
Inventor Signature

Inventor Name:	Fu-Liang Yang
Residence Address:	7F-3, No. 68, University Road Hsin-Chu City, Taiwan, R.O.C.

Dated:________________ ________________
Inventor Signature

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